

# **NOTES: UNLESS OTHERWISE SPECIFIED**

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS: REFLOW SOLDER TOP SIDE SMD.  
MAXIMUM SOLDER TEMPERATURE IS 240 DEG. C.
3. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS WHERE SHOWN.

5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. MARK ASSEMBLY VERSION WITH PERMANENT MARKER.
8. RESISTORS SHALL BE INSTALLED AT LOCATIONS C48 AND C50. SEE BILL OF MATERIALS.

